# SWITCHMODE Power Rectifiers

These state-of-the-art devices have the following features:

- Low Power Loss / High Efficiency
- New Package Provides Capability of Inspection and Probe After Board Mounting
- Guardring for Stress Protection
- Low Forward Voltage
- 175°C Operating Junction Temperature
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free and Halide-Free Devices

#### **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting SurfaceTemperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL 1 Requirements

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40	V
Average Rectified Forward Current (Rated V <sub>R</sub> , T <sub>C</sub> = 165°C)	I <sub>F(AV)</sub>	5	Α
Peak Repetitive Forward Current, (Rated V <sub>R</sub> , Square Wave, 20 kHz, T <sub>C</sub> = 165°C)	I <sub>FRM</sub>	10	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	150	Α
Storage Temperature Range	T <sub>stg</sub>	-65 to +175	°C
Operating Junction Temperature	$T_J$	-40 to +175	°C
Unclamped Inductive Switching Energy (10 mH Inductor, Non-repetitive)	E <sub>AS</sub>	40	mJ
ESD Rating (Human Body Model)		3B	
ESD Rating (Machine Model)		M4	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



#### ON Semiconductor®

http://onsemi.com

# SCHOTTKY BARRIER RECTIFIERS 5 AMPERES 40 VOLTS





# A B540 A BYWZZ

**MARKING** 

B540 = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

#### **ORDERING INFORMATION**

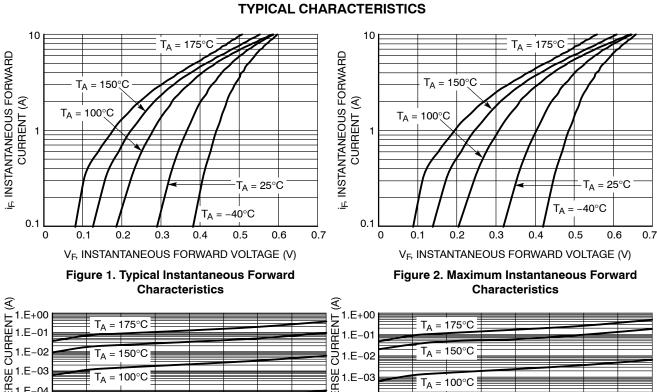
Device	Package	Shipping†
MBR540MFST1G	SO-8 FL (Pb-Free)	1500 / Tape & Reel
MBR540MFST3G	SO-8 FL (Pb-Free)	5000 / Tape & Reel
NRVB540MFST1G	SO-8 FL (Pb-Free)	1500 / Tape & Reel
NRVB540MFST3G	SO-8 FL (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Тур	Max	Unit
Thermal Resistance, Junction-to-Case, Steady State (Assumes 600 mm <sup>2</sup> 1 oz. copper bond pad, on a FR4 board)	$R_{ heta JC}$	-	4.0	°C/W
ELECTRICAL CHARACTERISTICS		-		
Instantaneous Forward Voltage (Note 1) ( $i_F = 5$ Amps, $T_J = 100^{\circ}$ C) ( $i_F = 5$ Amps, $T_J = 25^{\circ}$ C)	VF	0.44 0.50	0.54 0.58	V
Instantaneous Reverse Current (Note 1) (Rated dc Voltage, T <sub>J</sub> = 100°C) (Rated dc Voltage, T <sub>J</sub> = 25°C)	İR	6 0.100	20 2	mA

<sup>1.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.



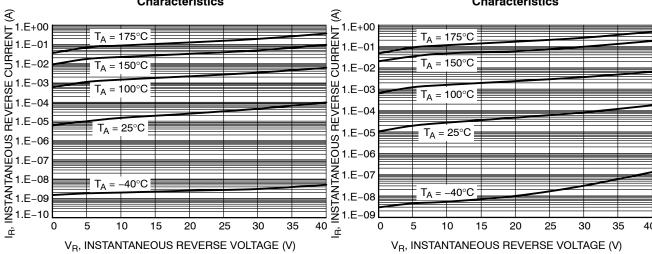


Figure 3. Typical Reverse Characteristics

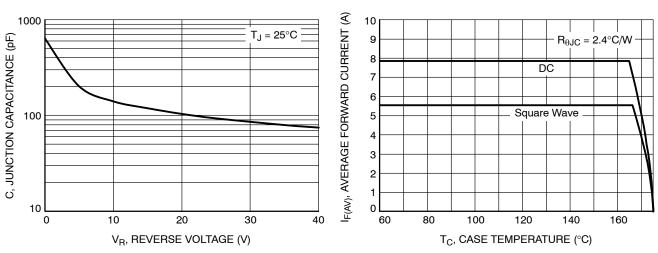
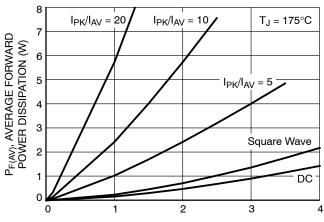


Figure 5. Typical Junction Capacitance

Figure 6. Current Derating TO-220AB

Figure 4. Maximum Reverse Characteristics

#### **TYPICAL CHARACTERISTICS**



I<sub>F(AV)</sub>, AVERAGE FORWARD CURRENT (A)

Figure 7. Forward Power Dissipation

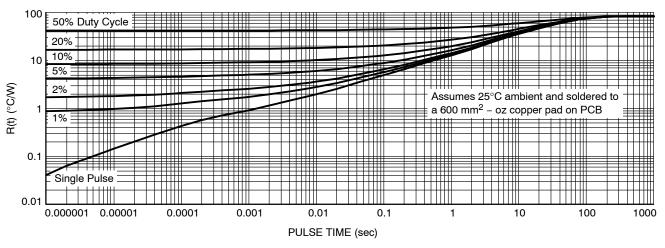
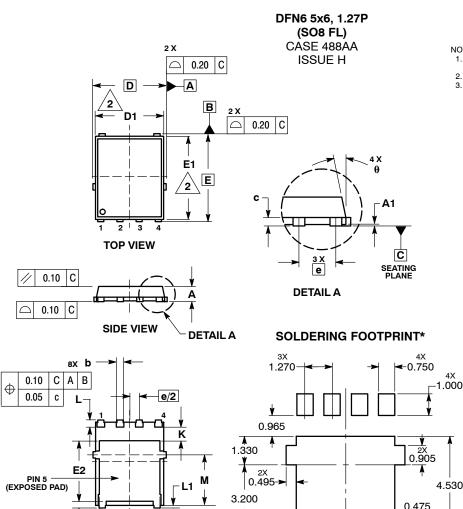


Figure 8. Thermal Characteristics

#### **PACKAGE DIMENSIONS**



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
   CONTROLLING DIMENSION: MILLIMETER.
- CONTROLLING DIMENSION: MILLIMETER.
   DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.90	1.00	1.10	
A1	0.00		0.05	
b	0.33	0.41	0.51	
С	0.23	0.28	0.33	
D	5.15 BSC			
D1	4.70	4.90	5.10	
D2	3.80	4.00	4.20	
E	6.15 BSC			
E1	5.70	5.90	6.10	
E2	3.45	3.65	3.85	
е	1.27 BSC			
G	0.51	0.61	0.71	
K	1.20	1.35	1.50	
L	0.51	0.61	0.71	
L1	0.05	0.17	0.20	
М	3.00	3.40	3.80	
θ	0 °		12 °	

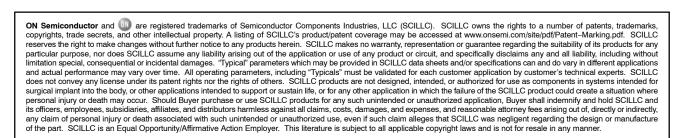
STYLE 2: PIN 1. ANODE

- 2. ANODE 3. ANODE
- 4. NO CONNECT
- 5. CATHODE

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

2X

→ 1.530 **→** 4.560——



#### PUBLICATION ORDERING INFORMATION

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**BOTTOM VIEW** 

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